

## Solder Paste No-Clean Sn96.5/Ag3.0/Cu0.5 60g T4 Mesh Two Part Mix™ [PATENT PENDING]

### Product Highlights

- 2 year shelf life unrefrigerated before mixed
- Printing speeds up to 100mm/sec
- Long stencil life
- Wide process window
- Clear residue
- Low voiding
- Excellent wetting compatibility on most board finishes
- Passes BONO test @1.56%
- RoHS II and REACH compliant

### Specifications

Alloy:	Sn96.5/Ag3.0/Cu0.5
Mesh Size:	T4
Micron (µm) Range:	20-38
Flux Type:	Synthetic No-Clean
Flux Classification:	RELO
Metal Load:	87% Metal by Weight
Melting Point:	217-220°C (423-428°F)
Packaging:	2 compartment bag, includes Jar for after mixed storage, 60g
Shelf Life:	Before Mixed: Refrigerated >24 months, Unrefrigerated >24 months After Mixed: Refrigerated >6 months, Unrefrigerated >2 months

### How to Mix the Two Parts

This product MUST BE MIXED within its bag before use. To mix, squeeze the flux pocket towards the solder powder pocket and the seal between the two compartments will break open, creating a single pocket bag. Then knead the mixture back and forth for 2-3 minutes, or until a uniform consistency is achieved.

### Printer Operation

- Print Speed: 25-100mm/sec
- Squeegee Pressure: 70-250g/cm of blade
- Under Stencil Wipe: Once every 10-25 prints, or as necessary

### Stencil Life

- >8 hours @ 20-50% RH 22-28°C (72-82°F)
- >4 hours @ 50-70% RH 22-28°C (72-82°F)

### Stencil Cleaning

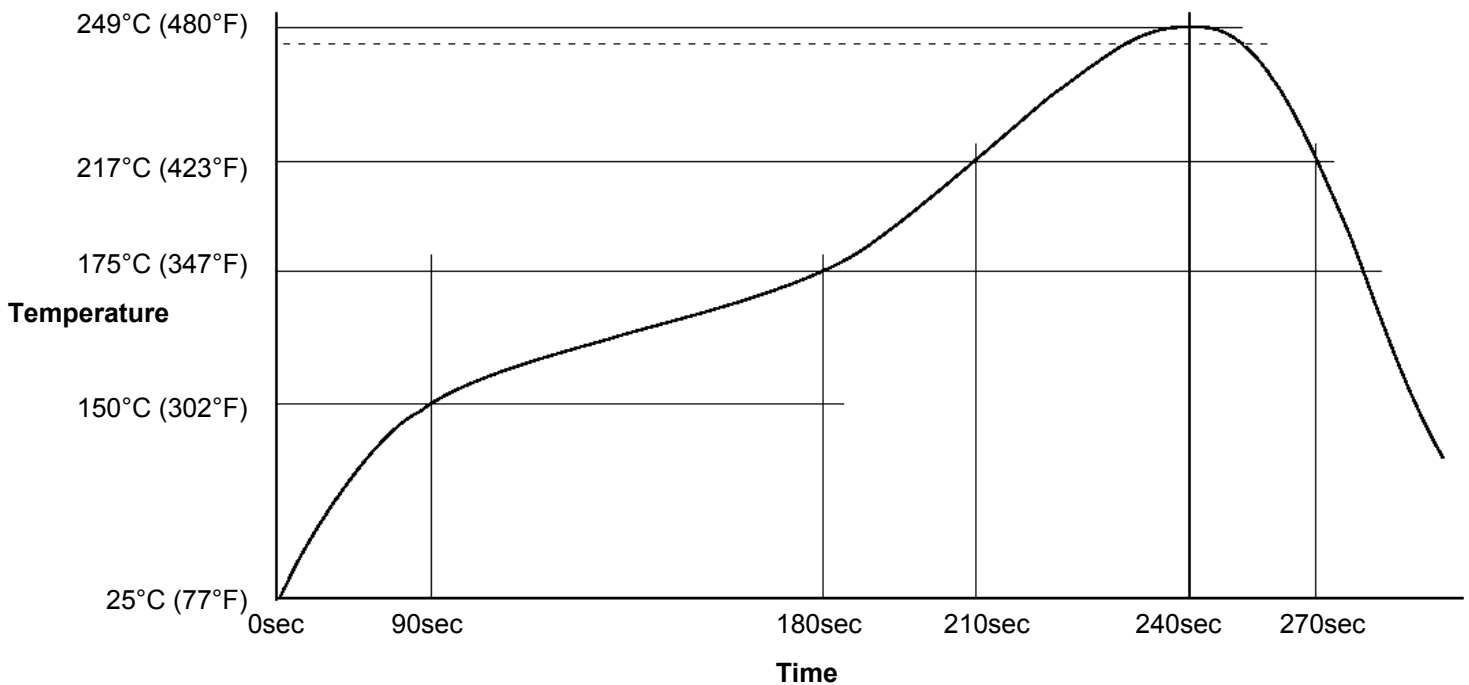
Automated stencil cleaning systems for both stencil and misprinted boards. Manual cleaning using isopropyl alcohol (IPA).

### Storage and Handling

- Before Mixed: Store refrigerated or at room temperature 3-25°C (37-77°F). Do not freeze.
- After Mixed: Refrigerate at 3-8°C (37-46°F). Do not freeze. Allow 4 hours for solder paste to reach an operating temperature of 20-25°C (68-77°F) before use. Once mixed, the solder paste can be dispensed by cutting a small corner off the bag. It can be resealed with a piece of Scotch® tape, or it can be stored by dispensing the entire bag into the provided empty jar.

## Recommended Profile

Reflow profile for Sn96.5/Ag3.0/Cu0.5 solder assembly, designed as a starting point for process optimization.



## Test Results

Test J-STD-004 or other requirements as stated	Test Requirement	Result
Copper Mirror	IPC-TM-650: 2.3.32	L: No breakthrough
Corrosion	IPC-TM-650: 2.6.15	L: No corrosion
Quantitative Halides	IPC-TM-650: 2.3.28.1	L: <0.5%
Electrochemical Migration	IPC-TM-650: 2.6.14.1	L: <1 decade drop (No-clean)
Surface Insulation Resistance 85°C, 85% RH @ 168 Hours	IPC-TM-650: 2.6.3.7	L: ≥100MΩ (No-clean)
Tack Value	IPC-TM-650: 2.4.44	64g
Viscosity – Malcom @ 10 RPM/25°C (x10 <sup>3</sup> mPa/s)	IPC-TM-650: 2.4.34.4	Print: 155-215, Dispense: 125-170
Visual	IPC-TM-650: 3.4.2.5	Clear and free from precipitation
Conflict Minerals Compliance	Electronic Industry Citizenship Coalition (EICC)	Compliant
REACH Compliance	Articles 33 and 67 of Regulation (EC) No 1907/2006	Contains no substance >0.1% w/w that is listed as a SVHC or restricted for use in solder materials

## Conforms to the following Industry Standards:

J-STD-004B, Amendment 1 (Solder Fluxes):	Yes
J-STD-005A (Solder Pastes):	Yes
J-STD-006C, Amendments 1 & 2 (Solder Alloys and Fluxed/Non-Fluxed Solders):	Yes
RoHS 2 Directive 2011/65/EU:	Yes